

RoHS Compliant Product
A suffix of "-C" specifies halogen free

DESCRIPTION

The SSU142N10SV-C is the Shielded Gate Technology N-ch MOSFETs with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

The SSU142N10SV-C meet the RoHS and Green Product requirement with full function reliability approved.

FEATURES

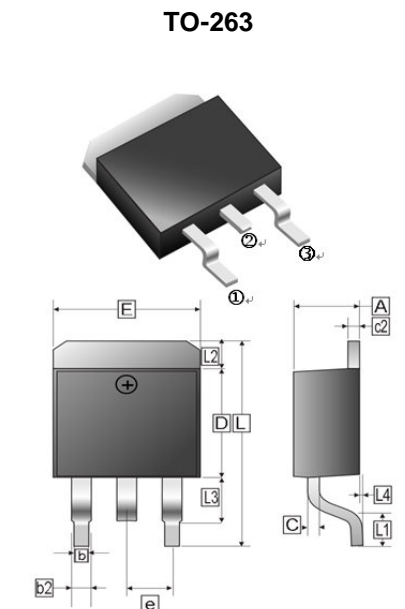
- Shielded Gate Trench Technology
- High Speed Power Switching
- Super Low Gate Charge
- Green Device Available

MARKING



PACKAGE INFORMATION

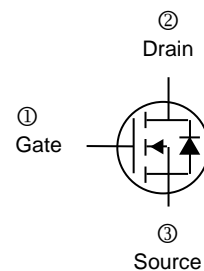
Package	MPQ	Leader Size
TO-263	0.8K	13 inch



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	4.00	4.87	c2	1.07	1.65
b	0.51	1.01	b2	1.34 REF.	
L4	0	0.30	D	8	9.65
C	0.30	0.74	e	2.54 REF.	
L3	1.50 REF.		L	14.60	16.10
L1	2.50 REF.		L2	1.27 REF.	
E	9.60	10.67			

ORDER INFORMATION

Part Number	Type
SSU142N10SV-C	Lead (Pb)-free and Halogen-free



ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹ @ $V_{GS}=10\text{V}$	I_D	$T_C=25^\circ\text{C}$	142
		$T_C=100^\circ\text{C}$	95
Pulsed Drain Current ²	I_{DM}	320	A
Power Dissipation ³	P_D	156.3	W
Operating Junction & Storage Temperature Range	T_J, T_{STG}	-55~150	$^\circ\text{C}$
Thermal Resistance Rating			
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	62	$^\circ\text{C/W}$
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	0.8	

ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	100	-	-	V	$V_{GS}=0V, I_D=250\mu A$	
Gate-Threshold Voltage	$V_{GS(th)}$	2	-	4	V	$V_{DS}=V_{GS}, I_D=250\mu A$	
Forward Transfer Conductance	g_{fs}	-	50	-	S	$V_{DS}=5V, I_D=30A$	
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 20V$	
Drain-Source Leakage Current	I_{DSS}	$T_J=25^\circ\text{C}$	-	-	1	μA	$V_{DS}=80V, V_{GS}=0V$
		$T_J=55^\circ\text{C}$	-	-	5		$V_{DS}=80V, V_{GS}=0V$
Static Drain-Source On-Resistance ²	$R_{DS(ON)}$	-	3.6	4.5	m Ω	$V_{GS}=10V, I_D=30A$	
Total Gate Charge	Q_g	-	72	-	nC	$I_D=20A$ $V_{DS}=50V$ $V_{GS}=10V$	
Gate-Source Charge	Q_{gs}	-	28	-			
Gate-Drain Change	Q_{gd}	-	15	-			
Turn-on Delay Time	$T_{d(on)}$	-	35	-	nS	$V_{DD}=50V$ $I_D=20A$ $V_{GS}=10V$ $R_G=3\Omega$	
Rise Time	T_r	-	18	-			
Turn-off Delay Time	$T_{d(off)}$	-	45	-			
Fall Time	T_f	-	55	-			
Input Capacitance	C_{iss}	-	4725	-	pF	$V_{GS}=0V$ $V_{DS}=50V$ $f=1MHz$	
Output Capacitance	C_{oss}	-	609	-			
Reverse Transfer Capacitance	C_{rss}	-	14	-			
Source-Drain Diode							
Diode Forward Voltage ²	V_{SD}	-	-	1.2	V	$I_S=50A, V_{GS}=0V$	
Continuous Source Current ¹	I_S	-	-	142	A	$V_G=V_D=0, \text{Force Current}$	
Reverse Recovery Time	T_{rr}	-	70	-	nS	$I_F=30A, di/dt=100A/\mu s,$ $T_J=25^\circ\text{C}$	
Reverse Recovery Charge	Q_{rr}	-	170	-	nC		

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. The power dissipation is limited by 150 $^\circ\text{C}$ junction temperature.

CHARACTERISTIC CURVES

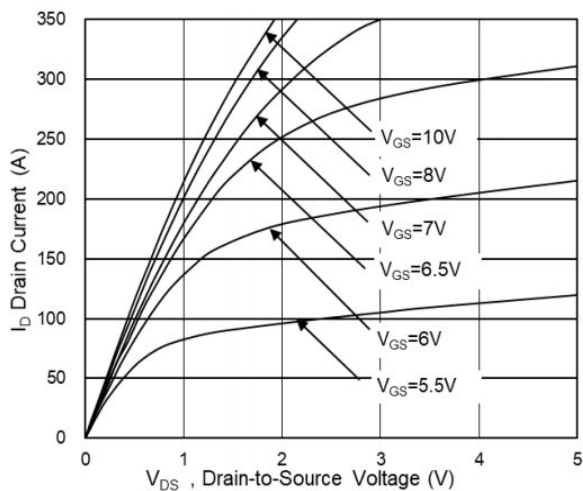


Fig.1 Typical Output Characteristics

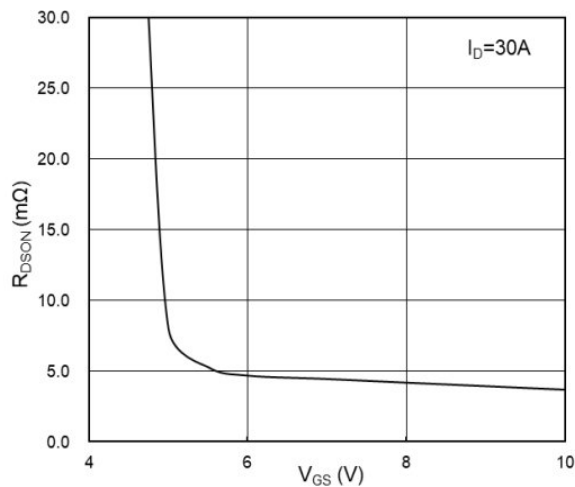


Fig.2 On-Resistance vs G-S Voltage

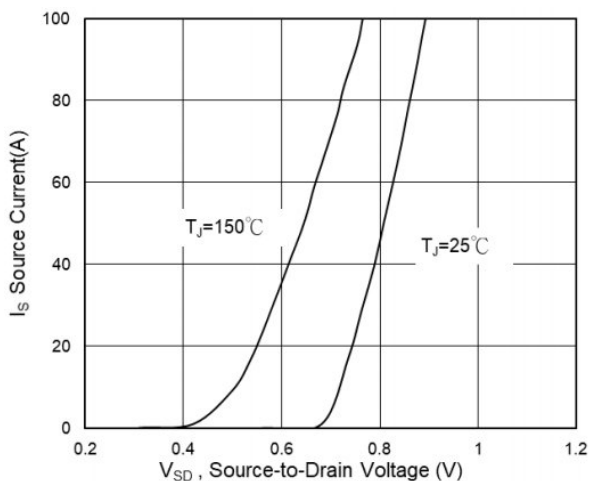


Fig.3 Source Drain Forward Characteristics

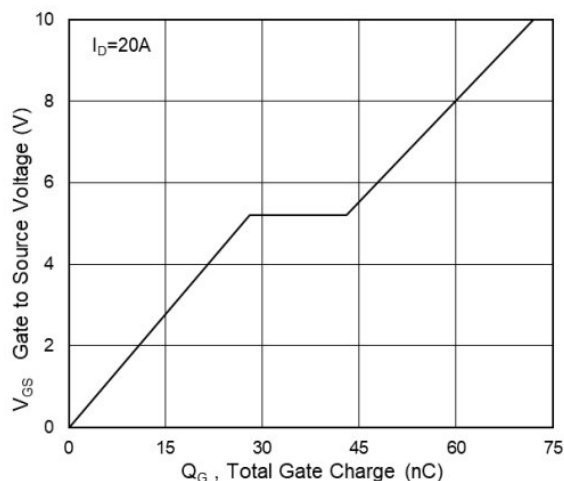


Fig.4 Gate-Charge Characteristics

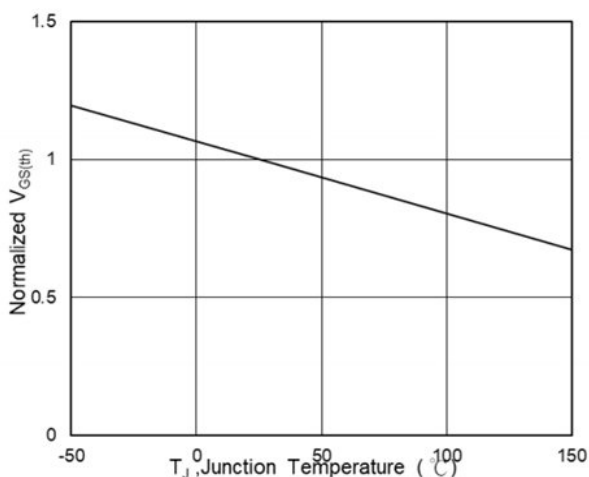


Fig.5 Normalized V_{TH} vs T_J

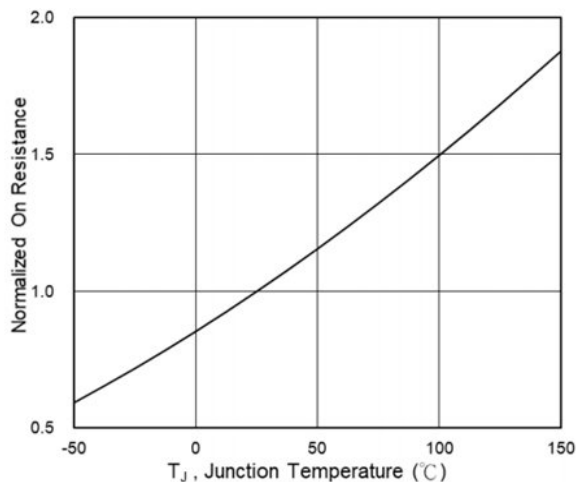


Fig.6 Normalized $R_{DS(ON)}$ vs T_J

CHARACTERISTIC CURVES

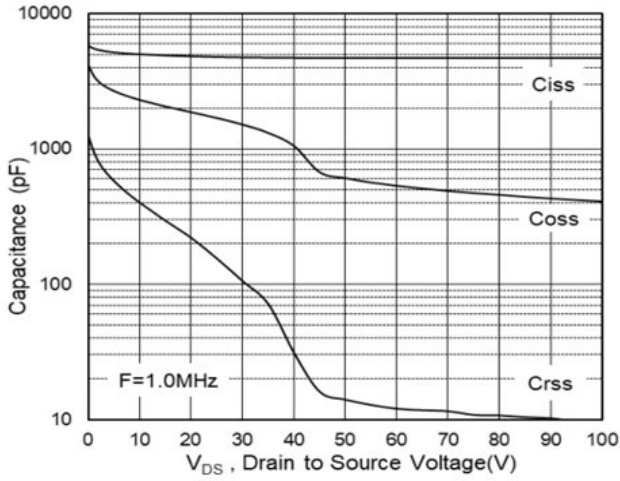


Fig.7 Capacitance

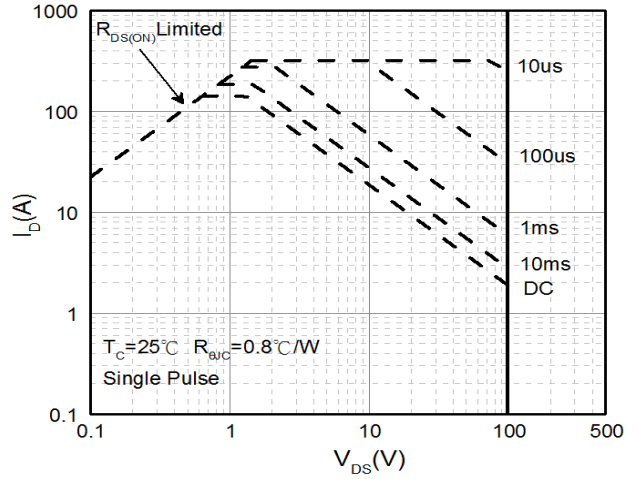


Fig.8 Safe Operating Area

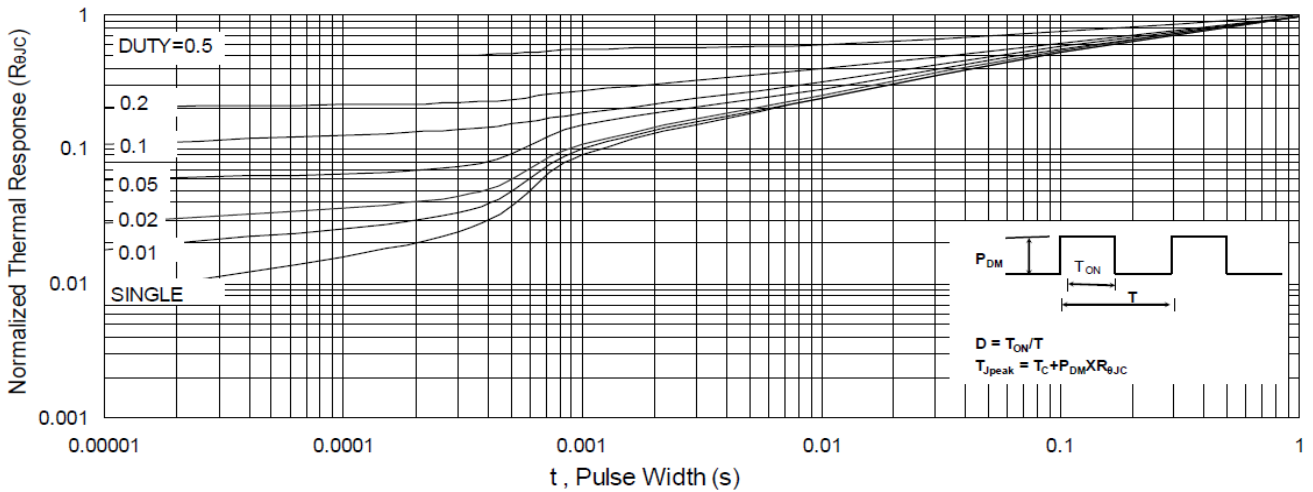


Fig.9 Normalized Maximum Transient Thermal Impedance

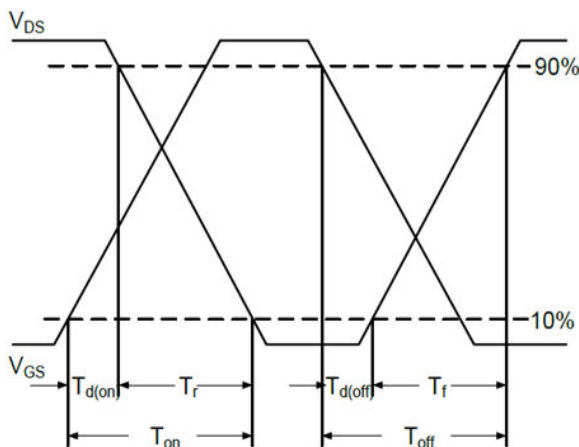


Fig.10 Switching Time Waveform

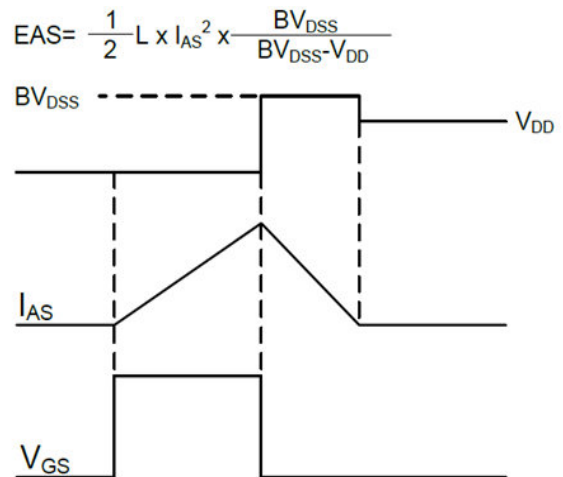


Fig.11 Unclamped Inductive Switching Waveform